

SHENMAO Introduces PF606-P26 Halogen Free No Clean Solder Paste



SHENMAO PF606-P26 No-Clean / Zero Halogen Solder Paste are made locally in the USA and with the same quality in 7 other world wide locations. It is said to prevent BGA Non-Wet Opens and Head on Pillow defects if there is oxidation on BGA Balls or PCB Pads. In case BGA components are warped, PF606-P26 thru excellent printability, wetting and solder ability can create highly reliable Solder Joints that greatly reduce their failure rate.

A Major Chipset Producer is recommending the use of SHENMAO PF606-P26 Solder Paste to achieve ultimately reliable connections to the PCB.

As the Worlds Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire, Solder Preform, Package on Package Solder Paste, Bumping Solder Paste, Low Temperature Solder Paste, Semiconductor Packaging Solder Spheres, Liquid Flux, Paste Flux and PV Ribbon.

For more information, please contact:

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